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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	16-Bit
Speed	32MHz
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, HLVD, POR, PWM, WDT
Number of I/O	18
Program Memory Size	8KB (2.75K x 24)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Through Hole
Package / Case	20-DIP (0.300", 7.62mm)
Supplier Device Package	20-PDIP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic24f08kl301-e-p

TABLE 1-5: PIC24F16KL20X/10X FAMILY PINOUT DESCRIPTIONS (CONTINUED)

Function	Pin Number			I/O	Buffer	Description
	20-Pin PDIP/ SSOP/ SOIC	20-Pin QFN	14-Pin PDIP/ TSSOP			
CVREF	17	14	11	I	ANA	Comparator Voltage Reference Output
CVREF+	2	19	2	I	ANA	Comparator Reference Positive Input Voltage
CVREF-	3	20	3	I	ANA	Comparator Reference Negative Input Voltage
HLVDIN	15	12	6	I	ST	High/Low-Voltage Detect Input
INT0	11	8	12	I	ST	Interrupt 0 Input
INT1	17	14	11	I	ST	Interrupt 1 Input
INT2	14	11	10	I	ST	Interrupt 2 Input
$\overline{MCLR}$	1	18	1	I	ST	Master Clear (device Reset) Input. This line is brought low to cause a Reset.
OSCI	7	4	4	I	ANA	Main Oscillator Input
OSCO	8	5	5	O	ANA	Main Oscillator Output
PGEC1	5	2	—	I/O	ST	ICSP™ Clock 1
PCED1	4	1	—	I/O	ST	ICSP Data 1
PGEC2	2	19	2	I/O	ST	ICSP Clock 2
PGED2	3	20	3	I/O	ST	ICSP Data 2
PGEC3	10	7	7	I/O	ST	ICSP Clock 3
PGED3	9	6	6	I/O	ST	ICSP Data 3
RA0	2	19	2	I/O	ST	PORTA Pins
RA1	3	20	3	I/O	ST	
RA2	7	4	4	I/O	ST	
RA3	8	5	5	I/O	ST	
RA4	10	7	7	I/O	ST	
RA5	1	18	1	I	ST	
RA6	14	11	10	I/O	ST	
RB0	4	1	—	I/O	ST	PORTB Pins
RB1	5	2	—	I/O	ST	
RB2	6	3	—	I/O	ST	
RB4	9	6	6	I/O	ST	
RB7	11	8	—	I/O	ST	
RB8	12	9	8	I/O	ST	
RB9	13	10	9	I/O	ST	
RB12	15	12	—	I/O	ST	
RB13	16	13	—	I/O	ST	
RB14	17	14	11	I/O	ST	
RB15	18	15	12	I/O	ST	
REFO	18	15	12	O	—	Reference Clock Output

Legend: TTL = TTL input buffer
ANA = Analog level input/output
ST = Schmitt Trigger input buffer
I^2C = I^2C™/SMBus input buffer

FIGURE 3-1: PIC24F CPU CORE BLOCK DIAGRAM

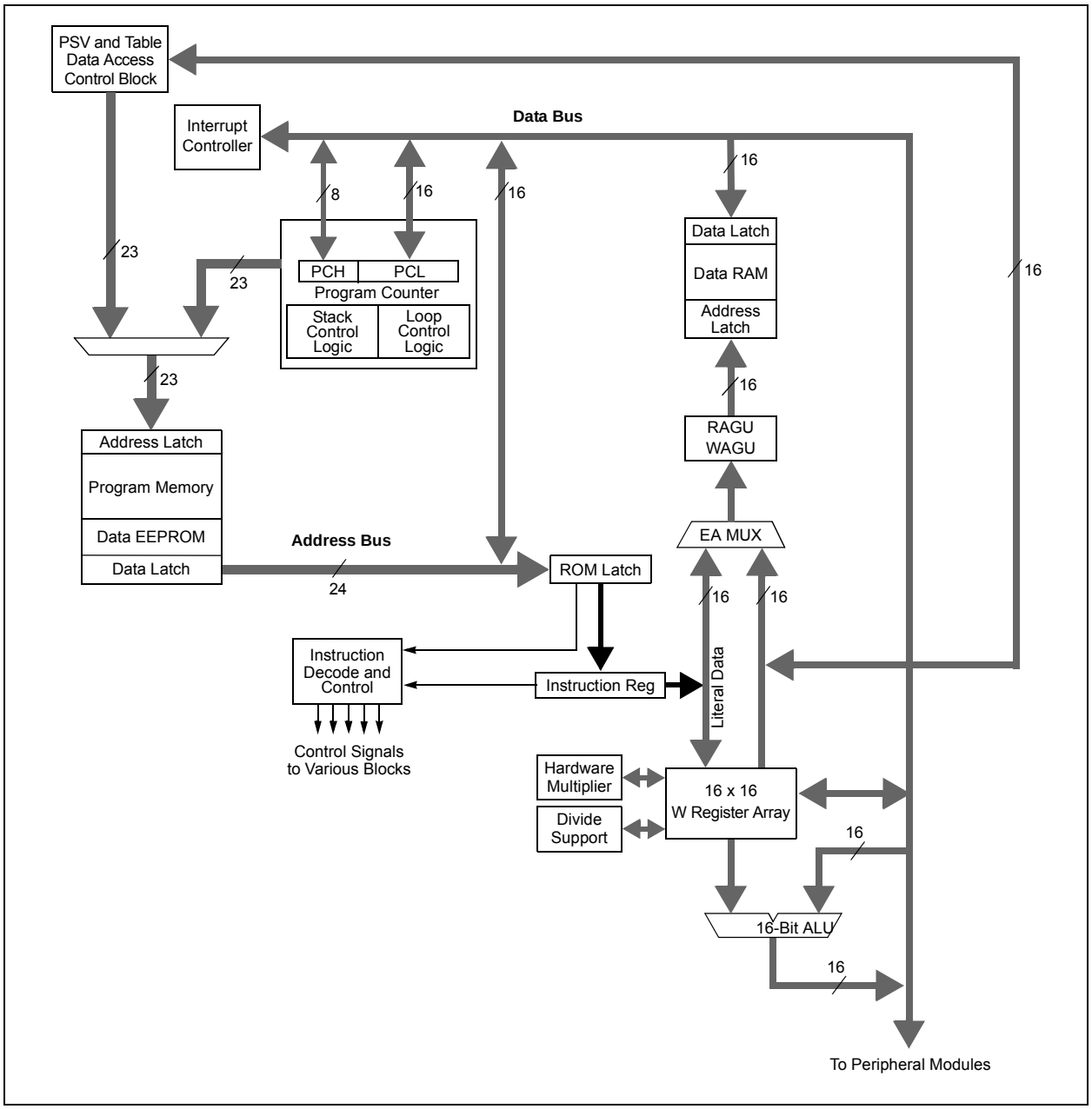


TABLE 3-1: CPU CORE REGISTERS

Register(s) Name	Description
W0 through W15	Working Register Array
PC	23-Bit Program Counter
SR	ALU STATUS Register
SPLIM	Stack Pointer Limit Value Register
TBLPAG	Table Memory Page Address Register
PSVPAG	Program Space Visibility Page Address Register
RCOUNT	REPEAT Loop Counter Register
CORCON	CPU Control Register

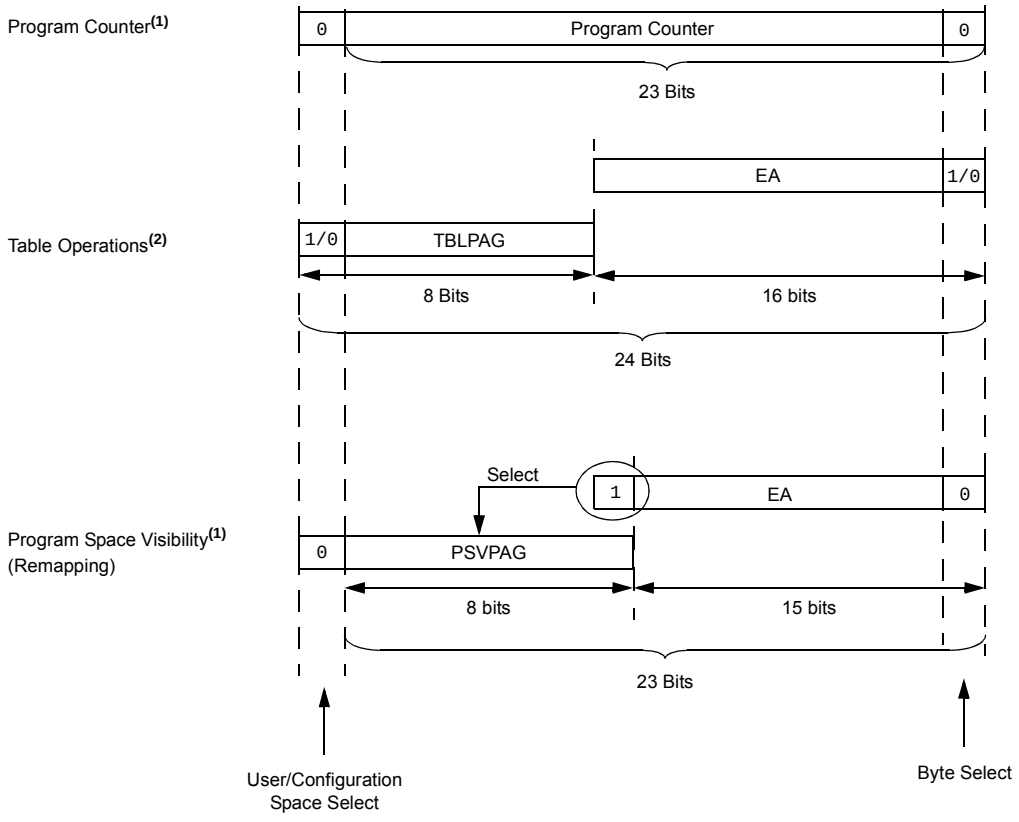
TABLE 4-20: PROGRAM SPACE ADDRESS CONSTRUCTION

Access Type	Access Space	Program Space Address				
		<23>	<22:16>	<15>	<14:1>	<0>
Instruction Access (Code Execution)	User	0	PC<22:1>			0
		0xx xxxx xxxx xxxx xxxx xxx0				
TBLRD/TBLWT (Byte/Word Read/Write)	User	TBLPAG<7:0>		Data EA<15:0>		
		0xxx xxxx		xxxx xxxx xxxx xxxx		
	Configuration	TBLPAG<7:0>		Data EA<15:0>		
		1xxx xxxx		xxxx xxxx xxxx xxxx		
Program Space Visibility (Block Remap/Read)	User	0	PSVPAG<7:0>(2)		Data EA<14:0>(1)	
		0	xxxx xxxx		xxx xxxx xxxx xxxx	

Note 1: Data EA<15> is always '1' in this case, but is not used in calculating the program space address. Bit 15 of the address is PSVPAG<0>.

2: PSVPAG can have only two values ('00' to access program memory and FF to access data EEPROM) on PIC24F16KL402 family devices.

FIGURE 4-5: DATA ACCESS FROM PROGRAM SPACE ADDRESS GENERATION



Note 1: The LSb of program space addresses is always fixed as '0' in order to maintain word alignment of data in the program and data spaces.

2: Table operations are not required to be word-aligned. Table read operations are permitted in the configuration memory space.

5.0 FLASH PROGRAM MEMORY

Note: This data sheet summarizes the features of this group of PIC24F devices. It is not intended to be a comprehensive reference source. For more information on Flash Programming, refer to the *"dsPIC33/PIC24 Family Reference Manual"*, **"Program Memory"** (DS39715).

The PIC24F16KL402 family of devices contains internal Flash program memory for storing and executing application code. The memory is readable, writable and erasable when operating with VDD over 1.8V.

Flash memory can be programmed in three ways:

- In-Circuit Serial Programming™ (ICSP™)
- Run-Time Self Programming (RTSP)
- Enhanced In-Circuit Serial Programming (Enhanced ICSP)

ICSP allows a PIC24F device to be serially programmed while in the end application circuit. This is simply done with two lines for the programming clock and programming data (which are named PGECx and PGEDx, respectively), and three other lines for power (VDD), ground (VSS) and Master Clear/Program mode Entry Voltage ($\overline{MCLR}$/VPP). This allows customers to manufacture boards with unprogrammed devices and then program the microcontroller just before shipping the product. This also allows the most recent firmware or custom firmware to be programmed.

Run-Time Self Programming (RTSP) is accomplished using TBLRD (Table Read) and TBLWT (Table Write) instructions. With RTSP, the user may write program memory data in blocks of 32 instructions (96 bytes) at a time, and erase program memory in blocks of 32, 64 and 128 instructions (96,192 and 384 bytes) at a time.

The NVMOP<1:0> (NVMCON<1:0>) bits decide the erase block size.

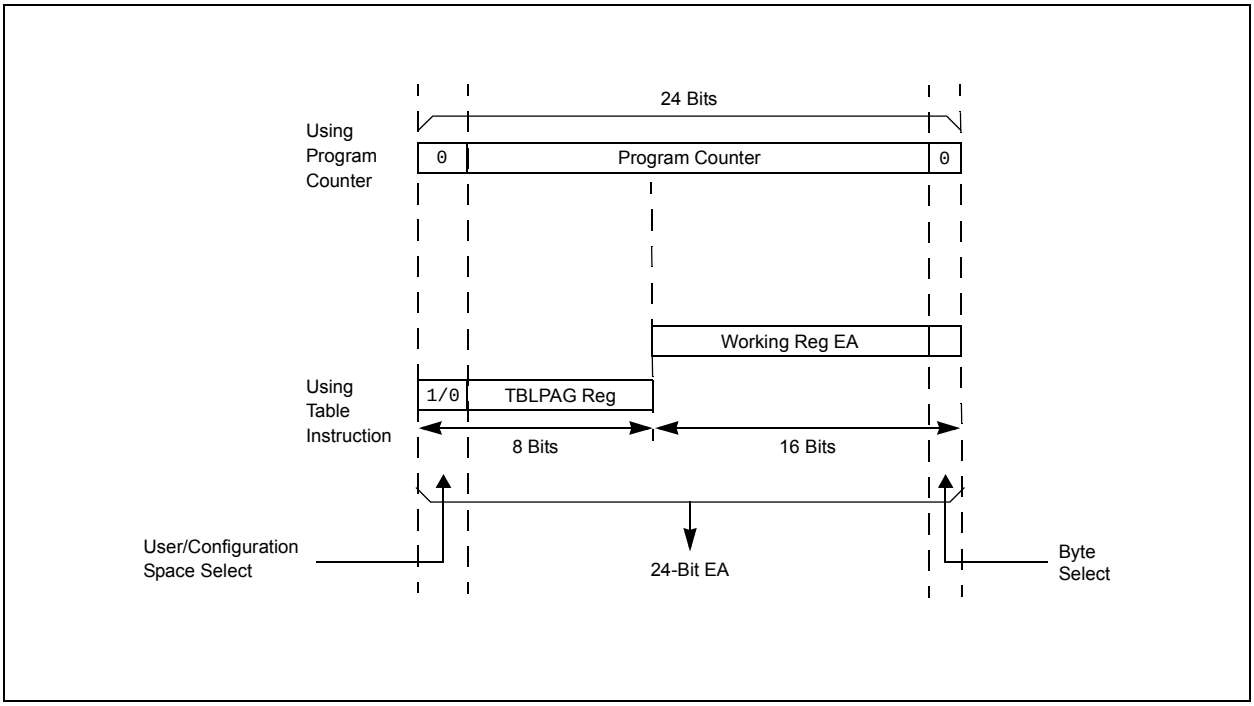
5.1 Table Instructions and Flash Programming

Regardless of the method used, Flash memory programming is done with the Table Read and Table Write instructions. These allow direct read and write access to the program memory space from the data memory while the device is in normal operating mode. The 24-bit target address in the program memory is formed using the TBLPAG<7:0> bits and the Effective Address (EA) from a W register, specified in the table instruction, as depicted in Figure 5-1.

The TBLRDL and TBLWTL instructions are used to read or write to bits<15:0> of program memory. TBLRDL and TBLWTL can access program memory in both Word and Byte modes.

The TBLRDH and TBLWTH instructions are used to read or write to bits<23:16> of program memory. TBLRDH and TBLWTH can also access program memory in Word or Byte mode.

FIGURE 5-1: ADDRESSING FOR TABLE REGISTERS



REGISTER 6-1: NVMCON: NONVOLATILE MEMORY CONTROL REGISTER

R/SO-0, HC	R/W-0	R/W-0	R/W-0	U-0	U-0	U-0	U-0
WR	WREN	WRERR	PGMONLY	—	—	—	—
bit 15							bit 8

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	ERASE	NVMOP5(1)	NVMOP4(1)	NVMOP3(1)	NVMOP2(1)	NVMOP1(1)	NVMOP0(1)
bit 7							bit 0

Legend:	HC = Hardware Clearable bit	U = Unimplemented bit, read as '0'	
R = Readable bit	W = Writable bit	SO = Settable Only bit	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **WR:** Write Control bit (program or erase)
1 = Initiates a data EEPROM erase or write cycle (can be set but not cleared in software)
0 = Write cycle is complete (cleared automatically by hardware)

bit 14 **WREN:** Write Enable bit (erase or program)
1 = Enables an erase or program operation
0 = No operation allowed (device clears this bit on completion of the write/erase operation)

bit 13 **WRERR:** Flash Error Flag bit
1 = A write operation is prematurely terminated (any $\overline{\text{MCLR}}$ or WDT Reset during programming operation)
0 = The write operation completed successfully

bit 12 **PGMONLY:** Program Only Enable bit
1 = Write operation is executed without erasing target address(es) first
0 = Automatic erase-before-write; write operations are preceded automatically by an erase of target address(es)

bit 11-7 **Unimplemented:** Read as '0'

bit 6 **ERASE:** Erase Operation Select bit
1 = Performs an erase operation when WR is set
0 = Performs a write operation when WR is set

bit 5-0 **NVMOP<5:0>:** Programming Operation Command Byte bits(1)
Erase Operations (when ERASE bit is '1'):
011010 = Erases 8 words
011001 = Erases 4 words
011000 = Erases 1 word
0100xx = Erases entire data EEPROM
Programming Operations (when ERASE bit is '0'):
001xxx = Writes 1 word

Note 1: These NVMOP configurations are unimplemented on PIC24F04KL10X and PIC24F08KL20X devices.

REGISTER 8-9: IFS4: INTERRUPT FLAG STATUS REGISTER 4

U-0	U-0	U-0	U-0	U-0	U-0	U-0	R/W-0
—	—	—	—	—	—	—	HLVDIF
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0	U-0
—	—	—	—	—	U2ERIF(1)	U1ERIF	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-9 **Unimplemented:** Read as '0'

bit 8 **HLVDIF:** High/Low-Voltage Detect Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 7-3 **Unimplemented:** Read as '0'

bit 2 **U2ERIF:** UART2 Error Interrupt Flag Status bit(1)
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 1 **U1ERIF:** UART1 Error Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 0 **Unimplemented:** Read as '0'

Note 1: This bit is unimplemented on PIC24FXXKL10X and PIC24FXXKL20X devices.

REGISTER 8-10: IFS5: INTERRUPT FLAG STATUS REGISTER 5

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	U-0	U-0	R/W-0
—	—	—	—	—	—	—	ULPWUIF
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-1 **Unimplemented:** Read as '0'

bit 0 **ULPWUIF:** Ultra Low-Power Wake-up Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

REGISTER 8-21: IPC4: INTERRUPT PRIORITY CONTROL REGISTER 4

U-0	R/W-1	R/W-0	R/W-0	U-0	R/W-1	R/W-0	R/W-0
—	CNIP2	CNIP1	CNIP0	—	CMIP2	CMIP1	CMIP0
bit 15							bit 8

U-0	R/W-1	R/W-0	R/W-0	U-0	R/W-1	R/W-0	R/W-0
—	BCL1IP2	BCL1IP1	BCL1IP0	—	SSP1IP2	SSP1IP1	SSP1IP0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **Unimplemented:** Read as ‘0’

bit 14-12 **CNIP<2:0>:** Input Change Notification Interrupt Priority bits
111 = Interrupt is Priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

bit 11 **Unimplemented:** Read as ‘0’

bit 10-8 **CMIP<2:0>:** Comparator Interrupt Priority bits
111 = Interrupt is Priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

bit 7 **Unimplemented:** Read as ‘0’

bit 6-4 **BCL1IP<2:0>:** MSSP1 I^2C™ Bus Collision Interrupt Priority bits
111 = Interrupt is Priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

bit 3 **Unimplemented:** Read as ‘0’

bit 2-0 **SSP1IP<2:0>:** MSSP1 SPI/I^2C Event Interrupt Priority bits
111 = Interrupt is Priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

8.4 Interrupt Setup Procedures

8.4.1 INITIALIZATION

To configure an interrupt source:

1. Set the NSTDIS Control bit (INTCON1<15>) if nested interrupts are not desired.
2. Select the user-assigned priority level for the interrupt source by writing the control bits in the appropriate IPCx register. The priority level will depend on the specific application and the type of interrupt source. If multiple priority levels are not desired, the IPCx register control bits, for all enabled interrupt sources, may be programmed to the same non-zero value.

Note:	At a device Reset, the IPCx registers are initialized, such that all user interrupt sources are assigned to Priority Level 4.

3. Clear the interrupt flag status bit associated with the peripheral in the associated IFSx register.
4. Enable the interrupt source by setting the interrupt enable control bit associated with the source in the appropriate IECx register.

8.4.2 INTERRUPT SERVICE ROUTINE

The method that is used to declare an ISR and initialize the IVT with the correct vector address depends on the programming language (i.e., C or assembler) and the language development toolsuite that is used to develop the application. In general, the user must clear the interrupt flag in the appropriate IFSx register for the source of the interrupt that the ISR handles. Otherwise, the ISR will be re-entered immediately after exiting the routine. If the ISR is coded in assembly language, it must be terminated using a `RETFIE` instruction to unstack the saved PC value, SRL value and old CPU priority level.

8.4.3 TRAP SERVICE ROUTINE (TSR)

A Trap Service Routine (TSR) is coded like an ISR, except that the appropriate trap status flag in the INTCON1 register must be cleared to avoid re-entry into the TSR.

8.4.4 INTERRUPT DISABLE

All user interrupts can be disabled using the following procedure:

1. Push the current SR value onto the software stack using the `PUSH` instruction.
2. Force the CPU to Priority Level 7 by inclusive ORing the value, OEh, with SRL.

To enable user interrupts, the `POP` instruction may be used to restore the previous SR value.

Only user interrupts with a priority level of 7 or less can be disabled. Trap sources (Levels 8-15) cannot be disabled.

The `DISI` instruction provides a convenient way to disable interrupts of Priority Levels 1-6 for a fixed period. Level 7 interrupt sources are not disabled by the `DISI` instruction.

13.0 TIMER2 MODULE

Note:	This data sheet summarizes the features of this group of PIC24F devices. It is not intended to be a comprehensive reference source. For more information on Timers, refer to the *"dsPIC33/PIC24 Family Reference Manual"*, **"Timers"** (DS39704).

The Timer2 module incorporates the following features:

- 8-bit Timer and Period registers (TMR2 and PR2, respectively)
- Readable and writable (both registers)
- Software programmable prescaler (1:1, 1:4 and 1:16)
- Software programmable postscaler (1:1 through 1:16)
- Interrupt on TMR2 to PR2 match
- Optional Timer3 gate on TMR2 to PR2 match
- Optional use as the shift clock for the MSSP modules

This module is controlled through the T2CON register (Register 13-1), which enables or disables the timer and configures the prescaler and postscaler. Timer2 can be shut off by clearing control bit, TMR2ON (T2CON<2>), to minimize power consumption.

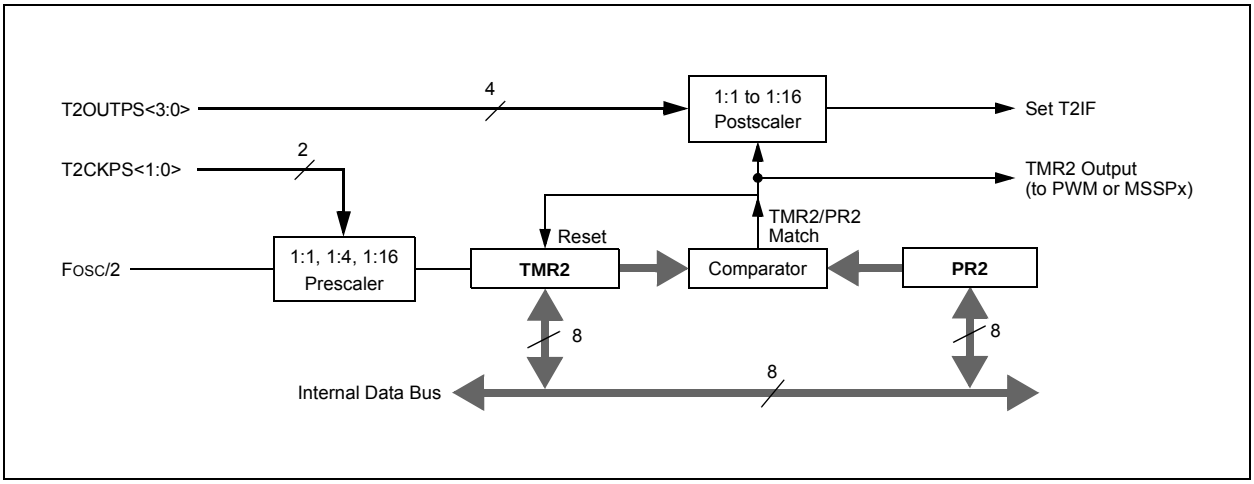
The prescaler and postscaler counters are cleared when any of the following occurs:

- A write to the TMR2 register
- A write to the T2CON register
- Any device Reset (POR, BOR, $\overline{\text{MCLR}}$ or WDT Reset)

TMR2 is not cleared when T2CON is written.

A simplified block diagram of the module is shown in Figure 13-1.

FIGURE 13-1: TIMER2 BLOCK DIAGRAM



REGISTER 16-1: CCPxCON: CCPx CONTROL REGISTER (STANDARD CCP MODULES)

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	DCxB1	DCxB0	CCPxM3(1)	CCPxM2(1)	CCPxM1(1)	CCPxM0(1)
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-6 **Unimplemented:** Read as '0'

bit 5-4 **DCxB<1:0>**: PWM Duty Cycle Bit 1 and Bit 0 for CCPx Module bits

Capture and Compare modes:
Unused.

PWM mode:
These bits are the two Least Significant bits (bit 1 and bit 0) of the 10-bit PWM duty cycle. The eight Most Significant bits (DCxB<9:2>) of the duty cycle are found in CCPRxL.

bit 3-0 **CCPxM<3:0>**: CCPx Module Mode Select bits(1)

1111 = Reserved
1110 = Reserved
1101 = Reserved
1100 = PWM mode
1011 = Compare mode: Special Event Trigger; resets timer on CCPx match (CCPxIF bit is set)
1010 = Compare mode: Generates software interrupt on compare match (CCPxIF bit is set, CCPx pin reflects I/O state)
1001 = Compare mode: Initializes CCPx pin high; on compare match, forces CCPx pin low (CCPxIF bit is set)
1000 = Compare mode: Initializes CCPx pin low; on compare match, forces CCPx pin high (CCPxIF bit is set)
0111 = Capture mode: Every 16th rising edge
0110 = Capture mode: Every 4th rising edge
0101 = Capture mode: Every rising edge
0100 = Capture mode: Every falling edge
0011 = Reserved
0010 = Compare mode: Toggles output on match (CCPxIF bit is set)
0001 = Reserved
0000 = Capture/Compare/PWM is disabled (resets CCPx module)

Note 1: CCPxM<3:0> = 1011 will only reset the timer and not start the A/D conversion on a CCPx match.

NOTES:

20.0 COMPARATOR MODULE

Note:	This data sheet summarizes the features of this group of PIC24F devices. It is not intended to be a comprehensive reference source. For more information on the Comparator module, refer to the *"dsPIC33/PIC24 Family Reference Manual"*, **"Dual Comparator Module"** (DS39710).

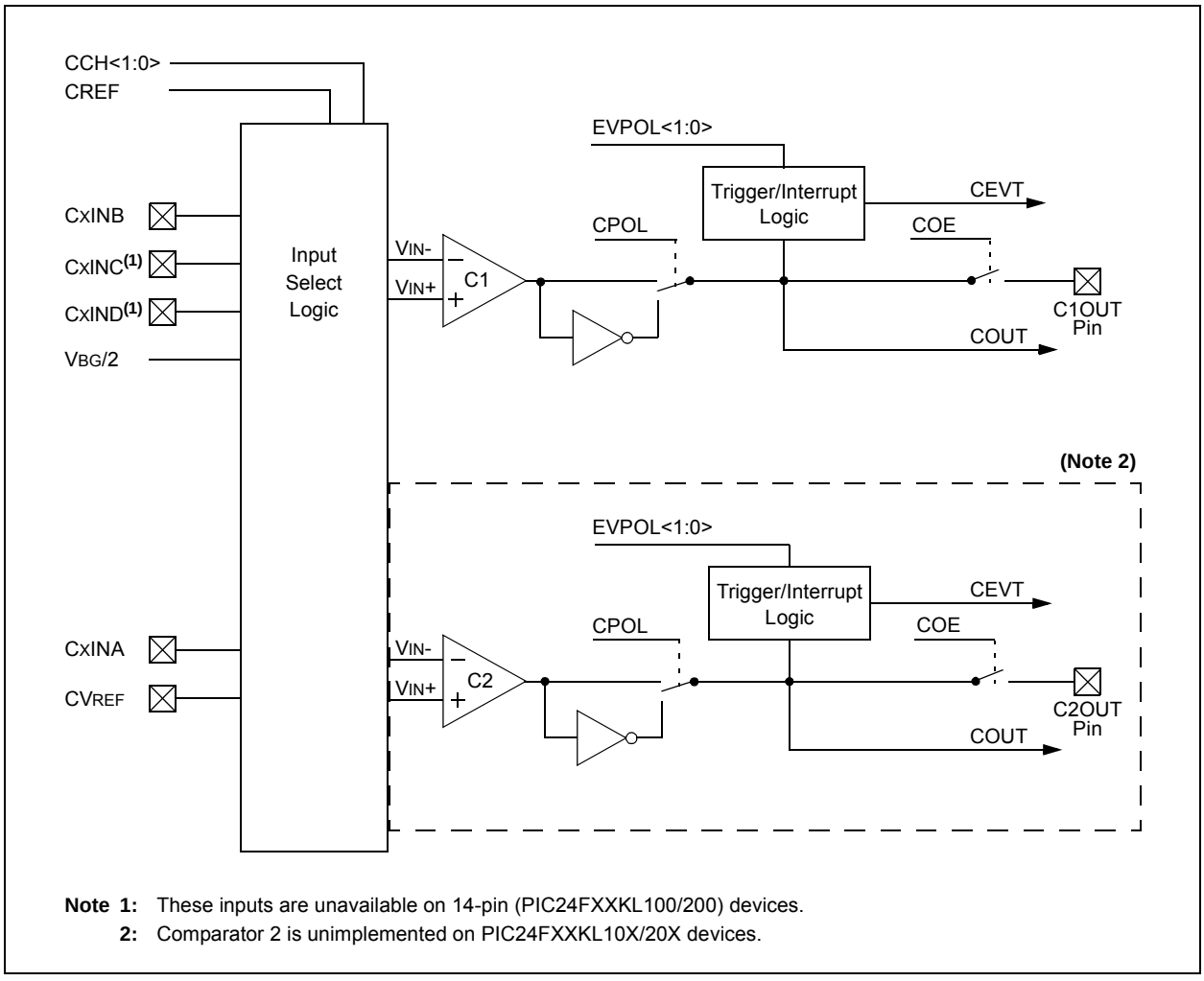
Depending on the particular device, the comparator module provides one or two analog comparators. The inputs to the comparator can be configured to use any one of up to four external analog inputs, as well as a voltage reference input from either the internal band gap reference, divided by 2 ($V_{BG}/2$), or the comparator voltage reference generator.

The comparator outputs may be directly connected to the CxOUT pins. When the respective COE equals '1', the I/O pad logic makes the unsynchronized output of the comparator available on the pin.

A simplified block diagram of the module is displayed in Figure 20-1. Diagrams of the possible individual comparator configurations are displayed in Figure 20-2.

Each comparator has its own control register, CMxCON (Register 20-1), for enabling and configuring its operation. The output and event status of all three comparators is provided in the CMSTAT register (Register 20-2).

FIGURE 20-1: COMPARATOR MODULE BLOCK DIAGRAM



Note 1: These inputs are unavailable on 14-pin (PIC24FXXKL100/200) devices.
2: Comparator 2 is unimplemented on PIC24FXXKL10X/20X devices.

22.0 HIGH/LOW-VOLTAGE DETECT (HLVD)

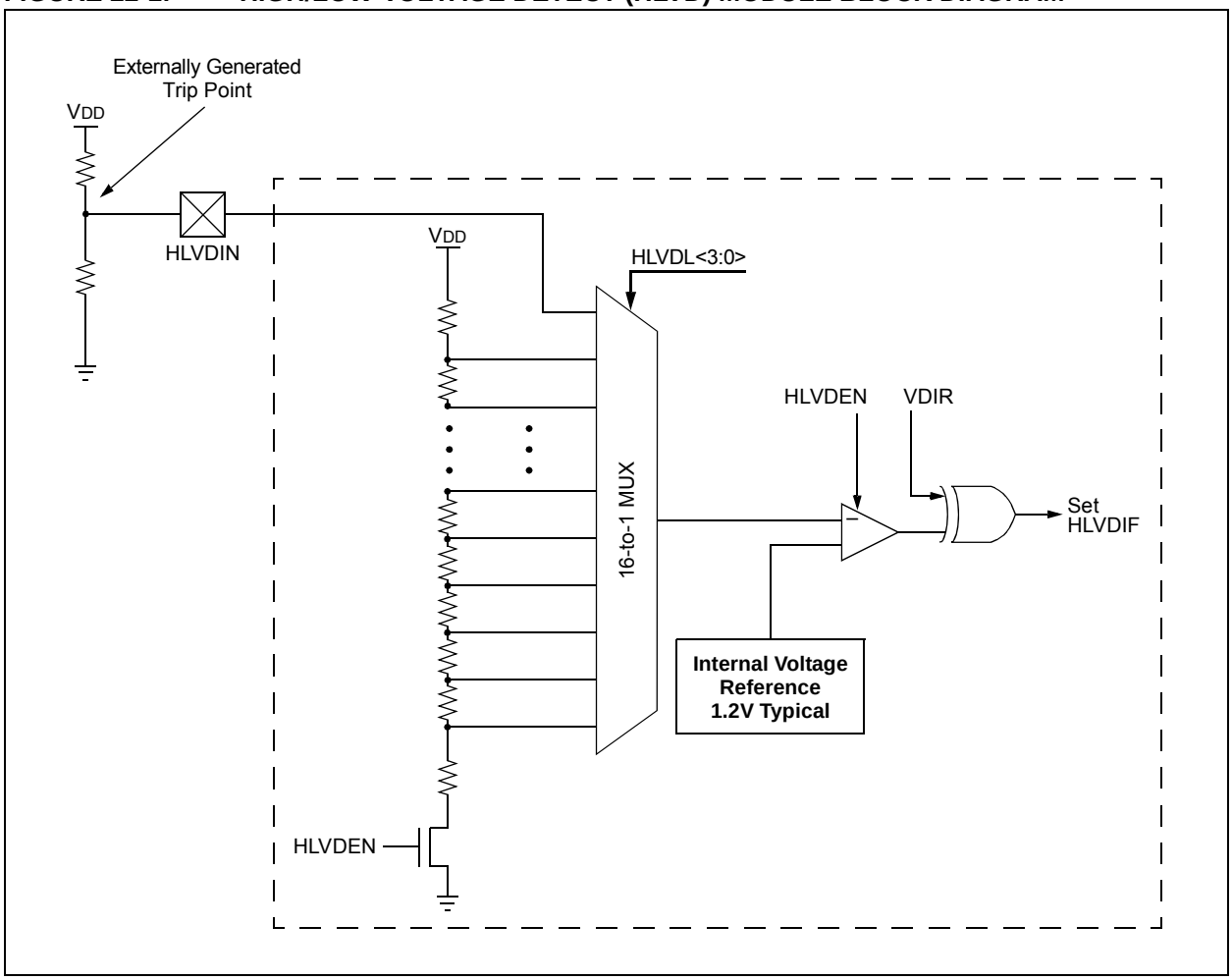
Note:	This data sheet summarizes the features of this group of PIC24F devices. It is not intended to be a comprehensive reference source. For more information on the High/Low-Voltage Detect, refer to the *"dsPIC33/PIC24 Family Reference Manual"*, **"High-Level Integration with Programmable High/Low-Voltage Detect (HLVD)"** (DS39725).

The High/Low-Voltage Detect module (HLVD) is a programmable circuit that allows the user to specify both the device voltage trip point and the direction of change.

An interrupt flag is set if the device experiences an excursion past the trip point in the direction of change. If the interrupt is enabled, the program execution will branch to the interrupt vector address and the software can then respond to the interrupt.

The HLVD Control register (see Register 22-1) completely controls the operation of the HLVD module. This allows the circuitry to be "turned off" by the user under software control, which minimizes the current consumption for the device.

FIGURE 22-1: HIGH/LOW-VOLTAGE DETECT (HLVD) MODULE BLOCK DIAGRAM



REGISTER 23-6: FPOR: RESET CONFIGURATION REGISTER

R/P-1	R/P-1	R/P-1	R/P-1	R/P-1	U-0	R/P-1	R/P-1
MCLRE(1)	BORV1(2)	BORV0(2)	I2C1SEL(3)	PWRTEN	—	BOREN1	BOREN0
bit 7							bit 0

Legend:			
R = Readable bit	P = Programmable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7 **MCLRE:** $\overline{\text{MCLR}}$ Pin Enable bit(1)
1 = $\overline{\text{MCLR}}$ pin is enabled; RA5 input pin is disabled
0 = RA5 input pin is enabled; $\overline{\text{MCLR}}$ is disabled

bit 6-5 **BORV<1:0>:** Brown-out Reset Enable bits(2)
11 = Brown-out Reset is set to the low trip point
10 = Brown-out Reset is set to the middle trip point
01 = Brown-out Reset is set to the high trip point
00 = Downside protection on POR is enabled (Low-Power BOR is selected)

bit 4 **I2C1SEL:** Alternate MSSP1 I^2C™ Pin Mapping bit(3)
1 = Default location for SCL1/SDA1 pins (RB8 and RB9)
0 = Alternate location for SCL1/SDA1 pins (ASCL1/RB6 and ASDA1/RB5)

bit 3 **PWRTEN:** Power-up Timer Enable bit
1 = PWRT is enabled
0 = PWRT is disabled

bit 2 **Unimplemented:** Read as '0'

bit 1-0 **BOREN<1:0>:** Brown-out Reset Enable bits
11 = BOR is enabled in hardware; SBOREN bit is disabled
10 = BOR is enabled only while device is active and disabled in Sleep; SBOREN bit is disabled
01 = BOR is controlled with the SBOREN bit setting
00 = BOR is disabled in hardware; SBOREN bit is disabled

Note 1: The MCLRE fuse can only be changed when using the VPP-Based ICSP™ mode entry. This prevents a user from accidentally locking out the device from the low-voltage test entry.
2: Refer to Table 26-5 for BOR trip point voltages.
3: Implemented in 28-pin devices only. This bit position must be programmed (= 1) in all other devices for I^2C functionality to be available.

24.0 DEVELOPMENT SUPPORT

The PIC® microcontrollers (MCU) and dsPIC® digital signal controllers (DSC) are supported with a full range of software and hardware development tools:

- Integrated Development Environment
  - MPLAB® X IDE Software
- Compilers/Assemblers/Linkers
  - MPLAB XC Compiler
  - MPASM™ Assembler
  - MPLINK™ Object Linker/ MPLIB™ Object Librarian
  - MPLAB Assembler/Linker/Librarian for Various Device Families
- Simulators
  - MPLAB X SIM Software Simulator
- Emulators
  - MPLAB REAL ICE™ In-Circuit Emulator
- In-Circuit Debuggers/Programmers
  - MPLAB ICD 3
  - PICkit™ 3
- Device Programmers
  - MPLAB PM3 Device Programmer
- Low-Cost Demonstration/Development Boards, Evaluation Kits and Starter Kits
- Third-party development tools

24.1 MPLAB X Integrated Development Environment Software

The MPLAB X IDE is a single, unified graphical user interface for Microchip and third-party software, and hardware development tool that runs on Windows®, Linux and Mac OS® X. Based on the NetBeans IDE, MPLAB X IDE is an entirely new IDE with a host of free software components and plug-ins for high-performance application development and debugging. Moving between tools and upgrading from software simulators to hardware debugging and programming tools is simple with the seamless user interface.

With complete project management, visual call graphs, a configurable watch window and a feature-rich editor that includes code completion and context menus, MPLAB X IDE is flexible and friendly enough for new users. With the ability to support multiple tools on multiple projects with simultaneous debugging, MPLAB X IDE is also suitable for the needs of experienced users.

Feature-Rich Editor:

- Color syntax highlighting
- Smart code completion makes suggestions and provides hints as you type
- Automatic code formatting based on user-defined rules
- Live parsing

User-Friendly, Customizable Interface:

- Fully customizable interface: toolbars, toolbar buttons, windows, window placement, etc.
- Call graph window

Project-Based Workspaces:

- Multiple projects
- Multiple tools
- Multiple configurations
- Simultaneous debugging sessions

File History and Bug Tracking:

- Local file history feature
- Built-in support for Bugzilla issue tracker

24.11 Demonstration/Development Boards, Evaluation Kits and Starter Kits

A wide variety of demonstration, development and evaluation boards for various PIC MCUs and dsPIC DSCs allows quick application development on fully functional systems. Most boards include prototyping areas for adding custom circuitry and provide application firmware and source code for examination and modification.

The boards support a variety of features, including LEDs, temperature sensors, switches, speakers, RS-232 interfaces, LCD displays, potentiometers and additional EEPROM memory.

The demonstration and development boards can be used in teaching environments, for prototyping custom circuits and for learning about various microcontroller applications.

In addition to the PICDEM™ and dsPICDEM™ demonstration/development board series of circuits, Microchip has a line of evaluation kits and demonstration software for analog filter design, KEELOQ® security ICs, CAN, IrDA®, PowerSmart battery management, SEEVAL® evaluation system, Sigma-Delta ADC, flow rate sensing, plus many more.

Also available are starter kits that contain everything needed to experience the specified device. This usually includes a single application and debug capability, all on one board.

Check the Microchip web page (www.microchip.com) for the complete list of demonstration, development and evaluation kits.

24.12 Third-Party Development Tools

Microchip also offers a great collection of tools from third-party vendors. These tools are carefully selected to offer good value and unique functionality.

- Device Programmers and Gang Programmers from companies, such as SoftLog and CCS
- Software Tools from companies, such as Gimpel and Trace Systems
- Protocol Analyzers from companies, such as Saleae and Total Phase
- Demonstration Boards from companies, such as MikroElektronika, Digilent® and Olimex
- Embedded Ethernet Solutions from companies, such as EZ Web Lynx, WIZnet and IPLogika®

TABLE 26-10: DC CHARACTERISTICS: I/O PIN INPUT SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 1.8V to 3.6V Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Sym**	**Characteristic**	**Min**	**Typ(1)**	**Max**	**Units**	**Conditions**
	VIL	**Input Low Voltage(4)**					
DI10		I/O Pins	VSS	—	0.2 VDD	V	
DI15		$\overline{MCLR}$	VSS	—	0.2 VDD	V	
DI16		OSCI (XT mode)	VSS	—	0.2 VDD	V	
DI17		OSCI (HS mode)	VSS	—	0.2 VDD	V	
DI18		I/O Pins with I2C™ Buffer	VSS	—	0.3 VDD	V	SMBus disabled
DI19		I/O Pins with SMBus Buffer	VSS	—	0.8	V	SMBus enabled
	VIH	**Input High Voltage(4,5)**					
DI20		I/O Pins:					
		with Analog Functions	0.8 VDD	—	VDD	V	
		Digital Only	0.8 VDD	—	VDD	V	
DI25		$\overline{MCLR}$	0.8 VDD	—	VDD	V	
DI26		OSCI (XT mode)	0.7 VDD	—	VDD	V	
DI27		OSCI (HS mode)	0.7 VDD	—	VDD	V	
DI28		I/O Pins with I2C Buffer:					
		with Analog Functions	0.7 VDD	—	VDD	V	
		Digital Only	0.7 VDD	—	VDD	V	
DI29		I/O Pins with SMBus	2.1	—	VDD	V	2.5V ≤ VPIN ≤ VDD
DI30	ICNPU	**CNx Pull-up Current**	50	250	500	μA	VDD = 3.3V, VPIN = VSS
DI31	IPU	**Maximum Load Current for Digital High Detection w/Internal Pull-up**	—	—	30	μA	VDD = 2.0V
			—	—	1000	μA	VDD = 3.3V
	IIL	**Input Leakage Current(2,3)**					
DI50		I/O Ports	—	0.050	±0.100	μA	VSS ≤ VPIN ≤ VDD, Pin at high-impedance
DI51		VREF+, VREF-, AN0, AN1	—	0.300	±0.500	μA	VSS ≤ VPIN ≤ VDD, Pin at high-impedance

Note 1: Data in "Typ" column is at 3.3V, +25°C unless otherwise stated.

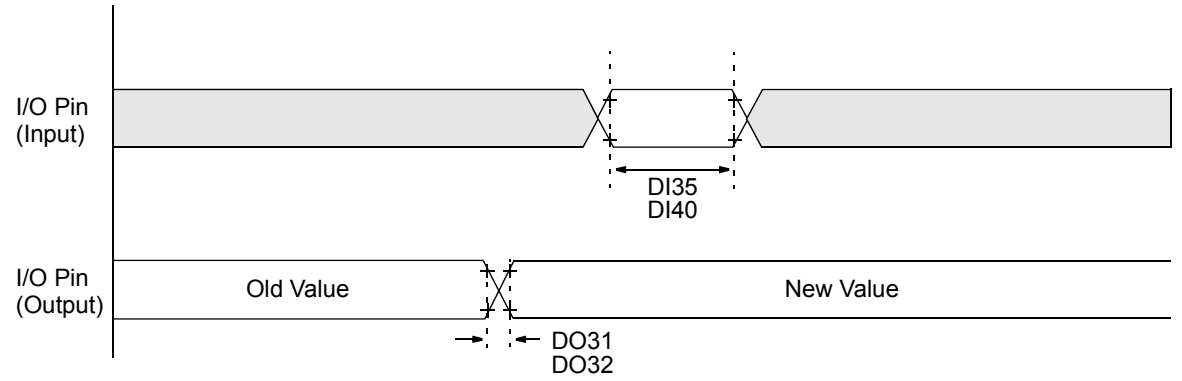
2: The leakage current on the $\overline{MCLR}$ pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as current sourced by the pin.

4: Refer to Table 1-4 and Table 1-5 for I/O pin buffer types.

5: VIH requirements are met when the internal pull-ups are enabled.

FIGURE 26-5: CLKO AND I/O TIMING CHARACTERISTICS



Note: Refer to Figure 26-3 for load conditions.

TABLE 26-22: CLKO AND I/O TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 1.8V to 3.6V Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Sym**	**Characteristic**	**Min**	**Typ(1)**	**Max**	**Units**	**Conditions**
DO31	TIOR	Port Output Rise Time	—	10	25	ns	
DO32	TIOF	Port Output Fall Time	—	10	25	ns	
DI35	TINP	INTx pin High or Low Time (output)	20	—	—	ns	
DI40	TRBP	CNx High or Low Time (input)	2	—	—	TCY	

Note 1: Data in "Typ" column is at 3.3V, +25°C unless otherwise stated.

TABLE 26-32: I²C™ BUS DATA REQUIREMENTS (SLAVE MODE)

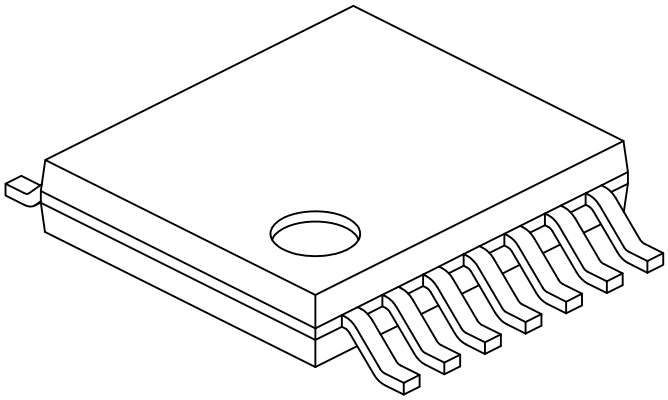
Param. No.	Symbol	Characteristic		Min	Max	Units	Conditions
100	THIGH	Clock High Time	100 kHz mode	4.0	—	µs	Must operate at a minimum of 1.5 MHz
			400 kHz mode	0.6	—	µs	Must operate at a minimum of 10 MHz
			MSSP module	1.5	—	TCY	
101	TLOW	Clock Low Time	100 kHz mode	4.7	—	µs	Must operate at a minimum of 1.5 MHz
			400 kHz mode	1.3	—	µs	Must operate at a minimum of 10 MHz
			MSSP module	1.5	—	TCY	
102	TR	SDAx and SCLx Rise Time	100 kHz mode	—	1000	ns	
			400 kHz mode	20 + 0.1 CB	300	ns	CB is specified to be from 10 to 400 pF
103	TF	SDAx and SCLx Fall Time	100 kHz mode	—	300	ns	
			400 kHz mode	20 + 0.1 CB	300	ns	CB is specified to be from 10 to 400 pF
90	TSU:STA	Start Condition Setup Time	100 kHz mode	4.7	—	µs	Only relevant for Repeated Start condition
			400 kHz mode	0.6	—	µs	
91	THD:STA	Start Condition Hold Time	100 kHz mode	4.0	—	µs	After this period, the first clock pulse is generated
			400 kHz mode	0.6	—	µs	
106	THD:DAT	Data Input Hold Time	100 kHz mode	0	—	ns	
			400 kHz mode	0	0.9	µs	
107	TSU:DAT	Data Input Setup Time	100 kHz mode	250	—	ns	**(Note 2)**
			400 kHz mode	100	—	ns	
92	TSU:STO	Stop Condition Setup Time	100 kHz mode	4.7	—	µs	
			400 kHz mode	0.6	—	µs	
109	TAA	Output Valid from Clock	100 kHz mode	—	3500	ns	**(Note 1)**
			400 kHz mode	—	—	ns	
110	TBUF	Bus Free Time	100 kHz mode	4.7	—	µs	Time the bus must be free before a new transmission can start
			400 kHz mode	1.3	—	µs	
D102	CB	Bus Capacitive Loading		—	400	pF	

Note 1: As a transmitter, the device must provide this internal minimum delay time to bridge the undefined region (min. 300 ns) of the falling edge of SCLx to avoid unintended generation of Start or Stop conditions.

2: A Fast mode I²C™ bus device can be used in a Standard mode I²C bus system, but the requirement, TSU:DAT ≥ 250 ns, must then be met. This will automatically be the case if the device does not stretch the LOW period of the SCLx signal. If such a device does stretch the LOW period of the SCLx signal, it must output the next data bit to the SDAx line, TR max. + TSU:DAT = 1000 + 250 = 1250 ns (according to the Standard mode I²C bus specification), before the SCLx line is released.

14-Lead Plastic Thin Shrink Small Outline (ST) - 4.4 mm Body [TSSOP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		14	
Pitch	e		0.65 BSC	
Overall Height	A	-	-	1.20
Molded Package Thickness	A2	0.80	1.00	1.05
Standoff	A1	0.05	-	0.15
Overall Width	E		6.40 BSC	
Molded Package Width	E1	4.30	4.40	4.50
Molded Package Length	D	4.90	5.00	5.10
Foot Length	L	0.45	0.60	0.75
Footprint	(L1)		1.00 REF	
Foot Angle	φ	0°	-	8°
Lead Thickness	c	0.09	-	0.20
Lead Width	b	0.19	-	0.30

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.15mm per side.
3. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.
REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing No. C04-087C Sheet 2 of 2